

L Number	Hits	Search Text	DB	Time stamp
5	12	Hirae and controller and clean\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 09:12
4	12	Hirae and Sadao and Sato and Masanobu and Yasuda and Shuichi	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 09:12
-	0	fushimi-ku.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:07
-	0	fushimiku.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:02
-	2812	fushimi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:02
-	1	"fushimi-ku" and sadao and masanobu and yasuda	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:04
-	338139	Hirae Sadao Sato Masanobu Yasuda Shuichi	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 15:14
-	1490	(Hirae Sadao Sato Masanobu Yasuda Shuichi) and ozone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:06
-	237	((Hirae Sadao Sato Masanobu Yasuda Shuichi) and ozone) and ultraviolet	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:06
-	93	((Hirae Sadao Sato Masanobu Yasuda Shuichi) and ozone) and ultraviolet and clean\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:07
-	27	((Hirae Sadao Sato Masanobu Yasuda Shuichi) and ozone) and ultraviolet and clean\$4 and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:13
-	0	degendt and ultraviolet and ozone and clean\$4 and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:14
-	3	degendt	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:36
-	84151	dainippon.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/03 14:36

-	16	dainippon.as. and wafer and ozone and clean	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 09:44
-	0	"242,4 nm"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 08:33
-	8	"242.4 nm"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 08:33
-	0	chapman near44 "1930" and ozone and nm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 08:41
-	118	chapman and ozone and nm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 08:41
-	53	chapman and ozone and nm and wavelength	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 13:54
-	19	chapman and ozone and nm and wavelength and clean	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 08:44
-	257	wafer and ozone and nm and wavelength and clean	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 09:03
-	58	wafer and ozone near12 UV and nm and wavelength and clean	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 09:04
-	16	dainippon.as. and wafer and ozone and clean	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 13:43
-	2	("5288333").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 13:41
-	11	((("5,975,098") or ("5,464,480") or ("6,403,498") or ("5,288,333") or ("20020088478"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 13:43
-	5	((("5,975,098") or ("5,464,480") or ("6,403,498") or ("5,288,333") or ("20020088478"))).PN.	USPAT; US-PGPUB	2002/09/06 13:43
-	3	dainippon.as. and wafer and ozone and clean and UV	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/06 13:43

-	2	("5464480").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 13:55
-	0	fushimi-ku.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 15:13
-	0	fushimi-ku.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 15:14
-	377399	Hirae Sadao Sato Masanobu Yasuda Shuichi	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 09:11
-	0	"09751000"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 07:12
-	1	"09/751000"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 07:12
-	54	UV and (rotate spin) and substrate and (nozzle orifice) and 134/.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/13 14:16
-	2	"63-15710"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/13 14:01
-	7	"6315710"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/13 14:01
-	0	"6315710" and uv	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/13 14:02
-	0	"6315710" and ultraviolet	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/13 14:02
-	0	"6315710" and light	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/13 14:02
-	0	"6315710" and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/13 14:02
-	79	UV and (rotat\$5 spin\$4) and substrate and (nozzle orifice) and 134/.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/13 14:17

-	3	photoresist near applicator and chuck and spin\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:09
-	4	photoresist near12 applicator and chuck and spin\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:09
-	1713	photoresist and chuck and spin\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:10
-	513	photoresist and chuck and spin\$4 and ultraviolet	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:10
-	224	photoresist and chuck near12 spin\$4 and ultraviolet	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:35
-	1	"4749440".PN.	USPAT	2004/06/22 10:15
-	1	"4765866".PN.	USPAT	2004/06/22 10:15
-	1	"4778532".PN.	USPAT	2004/06/22 10:16
-	1	"4778532".PN.	USPAT	2004/06/22 10:16
-	1	"4816098".PN.	USPAT	2004/06/22 10:16
-	1	"4904338".PN.	USPAT	2004/06/22 10:17
-	1	"4931103".PN.	USPAT	2004/06/22 10:17
-	187	chuck near12 spin\$4 and (UV ultraviolet) and (dispens\$4 coat\$3) and nozzle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:36
-	217	chuck near12 spin\$4 and (UV ultraviolet) and (dispens\$4 coat\$3) and nozzle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:37
-	1	"5626913".PN.	USPAT	2004/06/22 10:44
-	1	"5625433".PN.	USPAT	2004/06/22 10:44
-	1	"5252137".PN.	USPAT	2004/06/22 10:44
-	1	"4824763".PN.	USPAT	2004/06/22 10:44
-	3	"5910420"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:23
-	4	((("5464480") or ("6403498")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/05 12:35
-	0	controller near22 spin adj coat near33 (ultra\$violett UV)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 06:49
-	0	controller near22 spin adj coat near33 (cure ultra\$violett UV)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 06:49
-	0	controller near22 spin adj coat and (cure ultra\$violett UV)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 06:50

	1	controller near22 spin adj coat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/07 06:50
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Plurals

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 (1) "4904338".PN.
 (1) "4931103".PN.
 (187) chuck near12 spin\$4 and
 (217) chuck near12 spin\$4 and
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 (4) (("5464480") or ("6403498"
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 (0) controller near22 spin adj
 (1) controller near22 spin adj

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2	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 4161356 A	19790717	8	Apparatus for in-situ processing of photoplat	396/625	134/149; 134/153;		Giffin, et al.
3	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5078832 A	19920107	22	Method of treating wafer surface	216/94	134/1; 134/3;		Tanaka,
4	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5288333 A	19940222	25	Wafer cleaning method and apparatus therefore	134/31	134/11; 134/12;		Tanaka, al.
5	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5634980 A	19970603	11	Method for washing substrates	134/3	134/18; 134/33;	134/18	Tomita, al.
6	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5669979 A	19970923	41	Photoreactive surface processing	134/1	134/1.1; 134/1.2;	134/1;	Elliott et al.
7	<input type="checkbox"/>	<input type="checkbox"/>	US 5843527 A	19981201	60	Coating solution applying method and app	427/240	427/385.5; 438/782		Sanada,
8	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5966635 A	19991012	9	Method for reducing particles on a substrat		134/104.1; 134/153;		Hiatt, al.
9	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5975098 A	19991102	37	Apparatus for and method of cleaning subs	134/148	134/153; 134/181;		Yoshita Mitsua
10	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6491452 B2	20021210	10	Developing method and developing apparatus	396/611	118/52; 427/240		Konishi al.